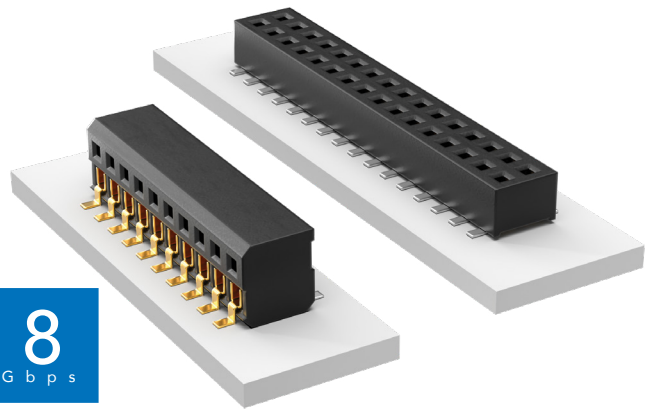


LOW PROFILE DUAL WIPE SOCKET

8
Gbps



(1.27 mm) .050" PITCH • CLP SERIES

CLP

Mates:

FTSH, FTS, FW



SPECIFICATIONS

Insulator Material:

Black Liquid Crystal Polymer

Contact Material:

Phosphor Bronze

Plating:

Sn or Au over

50 μ" (1.27 μm) Ni

Operating Temp Range:

-55 °C to +125 °C

Current Rating (CLP/FTSH):

3.4 A per pin

(2 pins powered)

Voltage Rating:

280 VAC/396 VDC

Insertion Depth:

Top Entry =

(1.40 mm) .055" minimum

Bottom Entry =

(2.41 mm) .095" minimum

plus board thickness

DH Entry =

(2.31 mm) .091" to (2.67 mm) .105"

Max Cycles:

100 with 10 μ" (0.25 μm) Au

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

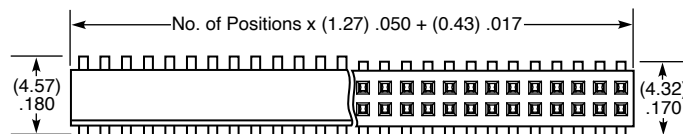
(0.10 mm) .004" max (02-35)

(0.15 mm) .006" max (36-50)*

*(.004" stencil solution

may be available; contact

ipg@samtec.com)

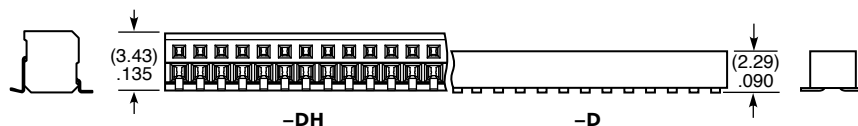


ALSO AVAILABLE

Contact Samtec

Single row

Other platings

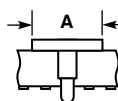


Notes:

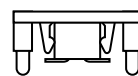
Severe Environment Testing qualified; aligns with MIL-DTL-55302. Visit samtec.com/set

Some lengths, styles and options are non-standard, non-returnable.

PIN/ROW	A
04-15	(3.56) .140
16-50	(7.11) .280



If odd pins/row, alignment pins are on middle position on centerline of the part.
If even pins/row, then alignment pins are between middle two positions.



-PA OPTION



-P OPTION